

RECOMMENDED HOLE PATTERN
TOLERANCE ±0.05

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FCI

spec ref		dr	Guo-Min Sun	2013/12/23	projection	mm	size	A3	scale	5:1
tolerance std		eng	Mike Zhou	2015/10/14			ecn no		ELX-N-22161-1	
TOLERANCES UNLESS OTHERWISE SPECIFIED		chr	-	-			rel level		Released	
surface		linear	0.X	±0.50		product family	dwg no		10127616	
			0.XX	±0.25			rev		C	
			0.XXX	±0.15			cat. no.		Product - Customer Drw	
		angular	0°	±3°	www.fci.com		STATUS: Released		Printed: Oct 26, 2015	

PRODUCT NUMBER DESCRIPTION:
10127616 - X XX X XX LF

PLATING: _____
1 = 15u" GXT ON CONATCT;
2 = 30u" GXT ON CONTACT;
3 = 80~200u" Tin ON CONTACT;

LEAD FREE

	LOSE PIN POSITION
01	7,8,15,16
02	7,8,15,16,23,24

PACKAGING:
A = TUBE W/O CAP

POSITIONS PER ROW = "N"
(02 ~ 25)

NOTES:

1. MATERIAL HOUSING: HIGH TEMPERATURE THERMOPLASTIC
UL 94V-0, COLOR BLACK

2. MATERIAL TERMINAL: COPPER ALLOY

3. TO DETERMINE DIMENSIONS:
N=NUMBER OF POSITIONS PER ROW
EX.: 10 POS., N x 2.00 = 20.00 TOTAL POSITIONS

4. 0.2kg MIN PER PIN RETENTION IN EITHER DIRECTION.

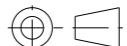
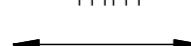

5. DIM 1.0 APPLIES TO MOLDED SIDE(S) ONLY. IF SIDE(S) ARE BROKEN,
DIM 1.5 MAX APPLIES.

6. P/N:10127616-XXXLF IS SAME AS P/N:10127616-XXX. THE SUFFIX 'LF'
IS ADDED FOR EASY LEAD FREE IDENTIFICATION.

7. THE HOUSING WILL WITHSTAND EXPOSURE TO 255~C PEAK
TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED
OR VAPOR PHASE REFLOW OVEN.

8. THE HOUSING WILL WITHSTAND EXPOSURE TO 260~C PEAK
TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER
APPLICATION WITH A 1.57MM MINIMUM THICK CIRCUIT BOARD.

9. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND
OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

dr	Guo-Min Sun	2013/12/23	projection 	mm 	size	A3	scale	8:1	
eng	Mike Zhou	2015/10/14			ecn no	ELX-N-22161-1			
chr	-	-			rel level	Released			
appr	Tim Yao	2015/10/26	product family	-					
		MINITEK 2.0mm HEADER			dwg no	10127616		rev	C
www.fci.com		cat. no. -			Product - Customer Drw		sheet 2 of 2		

